EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L45	176201	samsung with electronics	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/08 15:20
L46	192	(Je-hyoung with Ryu) (Sung-jin with Lee) (Jun-ho with Lee) (Tae-gyu with Kim)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/08 15:20
L47	176237	45 46	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/08 15:20
L48	1723	47 and (test$3 with (dut semiconductor))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/08 16:25
L49	7	47 and (test$3 with (dut semiconductor)) and ((heat with sink) radiator) and ((lead contact) with pusher) and (spring compress$4 flexib$4 resilient$2 elastic$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/08 16:26
L50	124	multiplex$3 with current with sink$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/08 15:37
L51	3	49 and ((thermal$2 conduct$3) with pad).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/08 15:53
L52	16	(test$3 with (dut semiconductor)) and ((heat with sink) radiator) and ((lead contact) with pusher) and (spring compress$4 flexib$4 resilient$2 elastic$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/08 16:06
L53	3	(test$3 with (dut semiconductor)) and ((heat with sink) radiator) and (pad with pusher) and (spring compress$4 flexib$4 resilient$2 elastic$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/08 16:24

L54	5825	702/33-35,108,117,118,121, 130-132,136,182.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/08 16:25
L55	65230	(test$3 with (dut semiconductor))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/08 17:00
L56	604	54 and 55	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/08 16:54
L57	16	(test$3 with (dut semiconductor)) and ((heat with sink) radiator) and ((lead contact) with pusher) and (spring compress$4 flexib$4 resilient$2 elastic$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/08 16:26
L58	238	54 and @pd>="20061121"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/08 16:44
L59	36	58 and 55	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/08 16:53
L60	10867	324/754-758,765.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/08 16:53
L61	5069	60 and 55	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/08 16:54
L62	6	60 and 57	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/08 16:59
L63	433	702/118,182.ccls.	US-PGPUB	OR	ON	2007/03/08 17:00

L64	9361	(test$3 with (dut semiconductor)). clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/08 17:00
L65	15	63 and 64	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/08 17:00